

BB02-EC :- 1.27mm x 2.54mm (0.05" x 0.1") DUAL ROW SOCKET, STRAIGHT, THROUGH HOLE - 6 TO 70 CONTACT

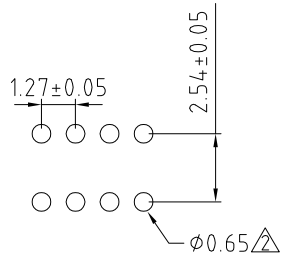
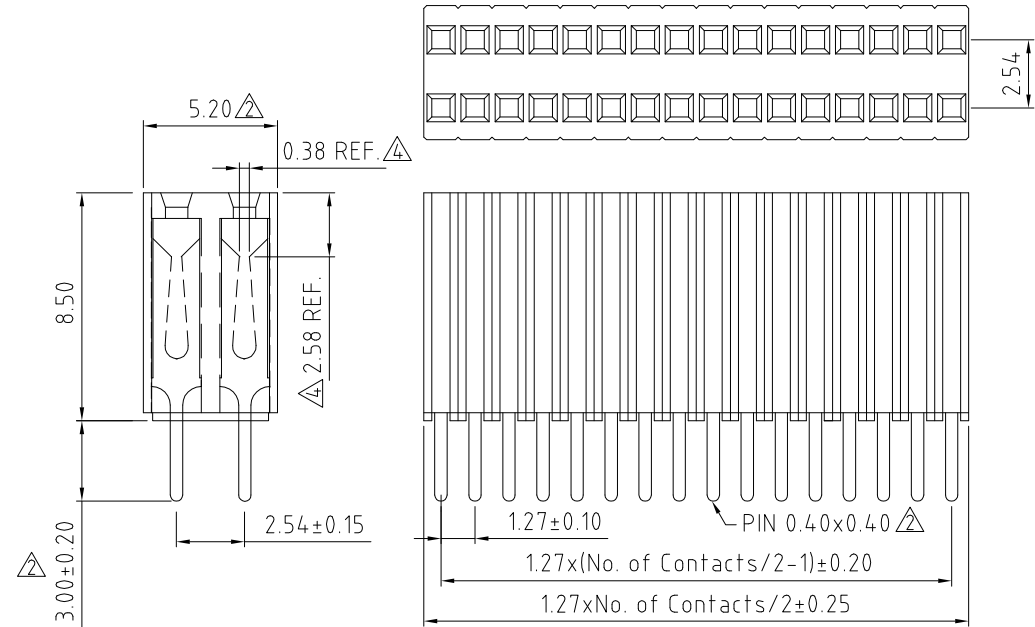
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD : LCP + 30% G/F
PLATING	GOLD, TIN OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC WAVE: 250°C FOR 5-10 SEC MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:

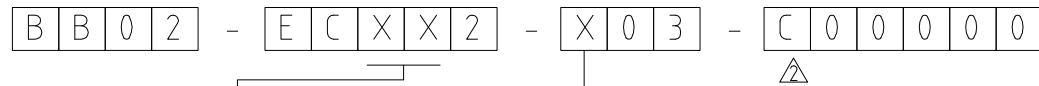
1. PACKED IN TUBE OR TRAY.
2. RECOMMENDED MATING PIN LENGTH: 4.5MM. Δ

MATES WITH :- BB02-DA
BB02-DE
BB02-DF
BB02-DG



RECOMMENDED PC BOARD HOLE LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS
 Δ 06 TO 70

CONTACT PLATING OPTIONS

- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN
- D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL
- E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
- F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
- G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL

10	23/06/02 - A.MCI RELEASE
11	17/02/05 - NYW DRAWING MODIFICATION
12	21/07/05 - NYW AMEND CONTACTS, AMEND INSULATOR DIM, AMEND PCB LAYOUT, AMEND PIN DIMENSION
13	24/07/06 - NYW DRAWING MODIFICATION
14	05/06/07 - NYW ADD CONTACT DIM, ADD NOTES 2
15	27/05/08 - CHC PLATING MODIFICATION
16	30/12/08 - CHC DRAWING MODIFICATION
17	20/05/11 - NYW CHANGE INSULATOR TO LCP

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X. ± 0.30 .X ± 0.25 .XX ± 0.15 .XXX ± 0.10	Material SEE NOTE
Drawn: CHC			
App'd: XXXX	Title SOCKET		NOT TO SCALE
Date: 20 MAY '11	Revision: 1.7		UNIT: mm

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Type: BB02-EC
BB02-EC
Drawing Number:
Sheet 1 of 1
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